Abstracts

Via Hole, Bond Wire and Shorting Pin Modeling for Multi-Layered Circuits

M.-J. Tsai, T.-S. Horng and N.G. Alexopoulos. "Via Hole, Bond Wire and Shorting Pin Modeling for Multi-Layered Circuits." 1994 MTT-S International Microwave Symposium Digest 94.3 (1994 Vol. III [MWSYM]): 1777-1780.

This paper presents a full-wave spectral-domain analysis to model generalized three-dimensional circuits for multi-layered structures. To describe properly the current along the vertical post, such as via holes, bond wires and shorting pins, etc, the simple pulse function is used in the procedure of the moment method. Several numerical techniques are applied to improve the evaluation of matrix elements. Comparison of numerical results with experimental and available analytical data shows good agreement.

❑ Return to main document.